

1111N(.110 x .110)

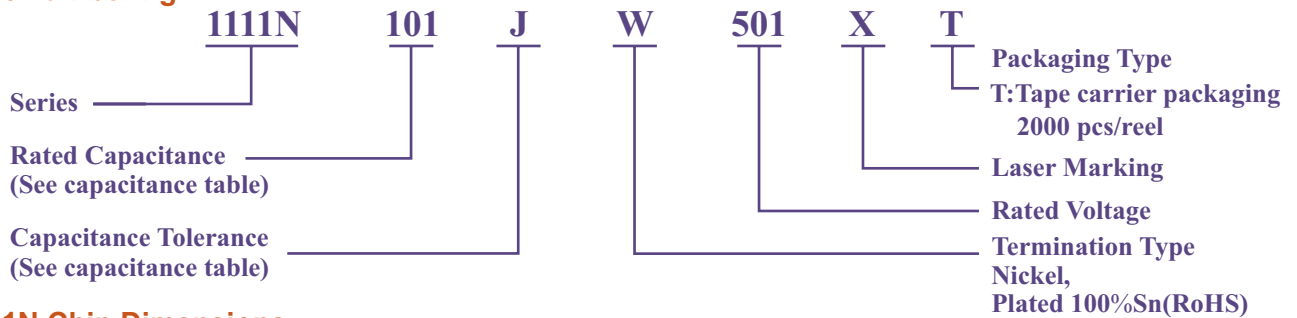


◆ **1111N Capacitance & Rated Voltage Table**

Cap.pF	Code	Tol.	WVDC V	Cap.pF	Code	Tol.	WVDC V	Cap.pF	Code	Tol.	WVDC V	Cap.pF	Code	Tol.	WVDC V			
0.5	0R5		500V Code 501 or 1000V Code 102	3.3	3R3	A, B, C, D	500V Code 501 or 1000V Code 102	24	240	F, G, J, K, M	500V Code 501 or 1000V Code 102	180	181	F, G, J, K, M	300 Code 301			
0.6	0R6			3.6	3R6				27			270			200	201		200V Code 201
0.7	0R7			3.9	3R9				30			300			220	221		
0.8	0R8			4.3	4R3				33			330			240	241		
0.9	0R9			4.7	4R7				36			360			270	271		
1.0	1R0			5.1	5R1				39			390			300	301		
1.1	1R1			5.6	5R6				43			430			330	331		
1.2	1R2			6.2	6R2				47			470			360	361		
1.3	1R3			6.8	6R8				51			510			390	391		
1.4	1R4			7.5	7R5				56			560			430	431		
1.5	1R5			8.2	8R2			62	620			470	471					
1.6	1R6			9.1	9R1			68	680			510	511		100V Code 101			
1.7	1R7			10	100	F, G, J, K, M		75	750			560	561					
1.8	1R8			11	110				82	820			620	621				
1.9	1R9			12	120				91	910			680	681				
2.0	2R0			13	130				100	101			750	751		50V Code 500		
2.1	2R1			15	150				110	111			820	821				
2.2	2R2			16	160				120	121			910	911				
2.4	2R4			18	180				130	131			1000	102				
2.7	2R7			20	200				150	151								
3.0	3R0			22	220				160	161								

Remark: special capacitance, tolerance and WVDC are available, consult with PASSIVE PLUS.

◆ **Part Numbering**



◆ **1111N Chip Dimensions**

unit: inch(millimeter)

	Length	Width	Thickness
1111N Chip Dimensions	0.110+0.020~-0.010 (2.79+0.51~-0.25)	.110 ± .010 (2.79 ± 0.25)	.10(2.6) max



◆ Performance

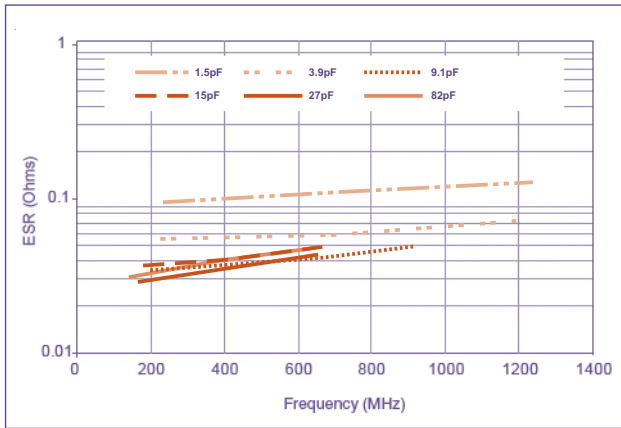
Quality Factor (Q)	2,000 min.
Insulation Resistance (IR)	10 ⁵ Megohms min. @ +25°C at rated WVDC. 10 ⁴ Megohms min. @ +125°C at rated WVDC.
Rated Voltage	See Capacitance Table
Dielectric Withstanding Voltage (DWV)	250% of rated voltage for 5 seconds.
Operating Temperature Range	-55°C to +125°C
Temperature Coefficient (TC)	0 ± 30ppm/°C
Capacitance Drift	± 0.02% or ± 0.02pF, whichever is greater.
Piezoelectric Effects	None

◆ Environmental Tests

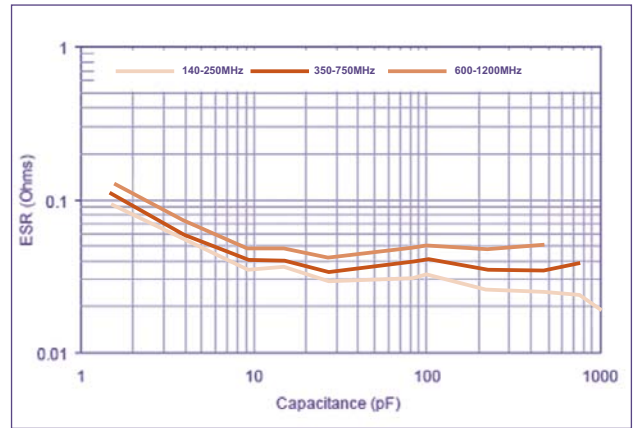
Item	Specifications	Method
Terminal Adhesion	Termination should not pull off. Ceramic should remain undamaged.	Linear pull force exerted on axial leads soldered to each terminal. 2.0lbs.
Resistance to soldering heat	No mechanical damage Capacitance change: - 1.0% ~ +2.0% Q>500 I.R. >10 G Ohms Breakdown voltage: 2.5 x WVDC	Preheat device to 150°C-180°C for 60 sec. Dip in 260°±5°C solder for 10±1 sec. Measure after 24±2 hour cooling period.
Thermal Shock	No mechanical damage Capacitance change:±0.5% or 0.5pF max Q>500 I.R. >10 G Ohms Breakdown voltage: 2.5 x WVDC	MIL-STD-202, Method 107, Condition A. At the maximum rated temperature (-55°C and 125°C) stay 30 minutes. The time of removing shall not be more than 3 minutes. Perform the five cycles.
Humidity, Steady State	No mechanical damage Capacitance change: ±0.5% or 0.5pF max. Q>300 I.R. >1 G Ohms Breakdown voltage: 2.5 x WVDC	MIL-STD-202, Method 106.
Low Voltage Humidity	No mechanical damage Capacitance change: ±0.3% or 0.3pF max. Q>300 I.R. >1 G Ohms Breakdown voltage: 2.5 x WVDC	MIL-STD-202, Method 103, Condition A, with 1.5 Volts D.C. applied while subjected to an environment of 85°C with 85% relative humidity for 240 hours minimum.
Life	No mechanical damage Capacitance change: ±2.0% or 0.5pF max. Q>500 I.R. >1 G Ohms Breakdown voltage: 2.5 x WVDC	MIL-STD-202, Method 108, for 1000 hours, at 125°C. 200% Rated voltage D.C. applied.

◆ **1111N Performance Curve**

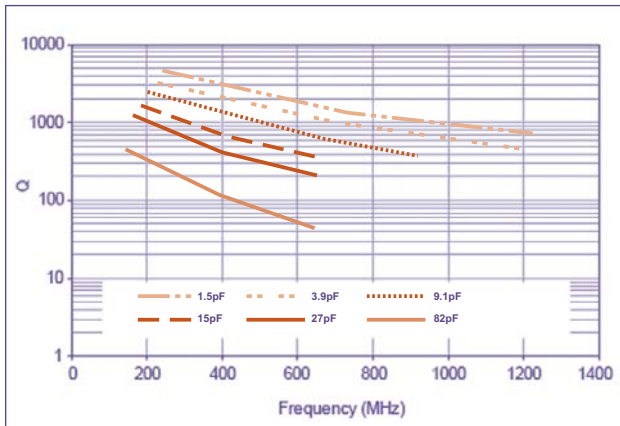
ESR vs Frequency



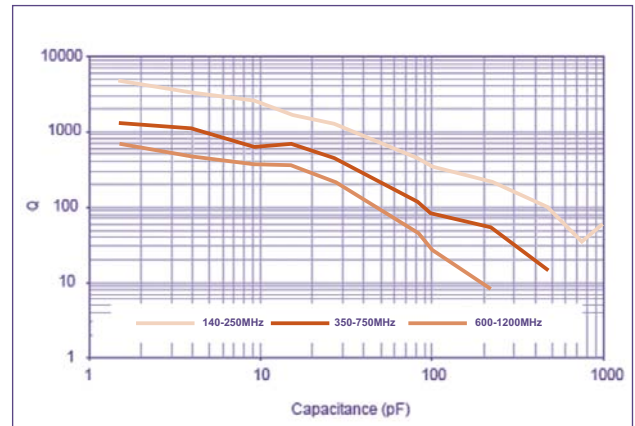
ESR vs Capacitance



Q vs Frequency



Q vs Capacitance



Series Resonant Frequency vs Capacitance

